



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-04-28
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Flavio Di Francesco	Representative Title	AMS Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	GYNB*0158BG6	A	Z6HA	2015-04-28
Amount	UoM	Unit type	ST ECOPACK Grade	
8.07	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	2 - 2 - 0.6	8	No lead	
Comment	Package:UFSON 2x2x0.6 8 PITCH 0.5; MD valid for LM258QT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014			
Query			Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH			true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application
			ppm in product

Material Composition Declaration						Mfr Item Name	GYNB*0158BG6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.718	mg	supplier	die	Silicon (Si)	7440-21-3		0.705	mg	981894	87361
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	8357	743
Silicon die				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	4178	372
Silicon die				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	5571	496
Leadframe	Copper and its alloy	3.092	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.905	mg	939521	359975
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.016	mg	5175	1983
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.106	mg	34282	13135
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.004	mg	1294	496
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	970	372
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.016	mg	5175	1983
Leadframe				supplier	alloy	Manganese (Mn)	7439-96-5		0.002	mg	647	248
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.036	mg	11643	4461
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	970	372
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	323	124
Die attach	Other inorganic materials	0.119	mg	supplier	glue or tape (choose)	Epoxyde Bisphenol A Resin	25068-38-6		0.011	mg	92437	1363
Die attach				supplier	glue or tape	Silica, vitreous	60676-86-0		0.036	mg	302521	4461
Die attach				supplier	glue or tape	Ethoxyethoxy-ethyl Acetate	112-15-2		0.026	mg	218487	3222
Die attach				supplier	glue or tape	Aluminium oxide	1344-28-1		0.024	mg	201681	2974
Die attach				supplier	glue or tape	Bisphenol A diglycidyl ether polymer	25036-25-3		0.017	mg	142857	2107
Die attach				supplier	glue or tape	Glycol ether ester	Proprietary		0.002	mg	16807	248
Die attach				supplier	glue or tape	Diaminodiphenylsulfone	80-08-0		0.002	mg	16807	248
Die attach				supplier	glue or tape	Aminopropyltriethoxysilane	919-30-2		0.001	mg	8403	124
Bonding wire	Precious metals	0.05	mg	supplier	wire	Gold (Au)	7440-57-5		0.05	mg	1000000	6196
encapsulation	Other inorganic materials	4.091	mg	supplier	mold compound	Silica Fused	60676-86-0		3.583	mg	875825	443990
encapsulation				supplier	mold compound	Epoxy Resin	85954-11-6		0.242	mg	59154	29988
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		0.242	mg	59154	29988
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.024	mg	5867	2974